Semiconductor Solutions for High Speed Communications and Fiber Optic Applications

The Infineon Resilient Ring Processor is a packet optimized transport engine designed to enable the first generation of Resilient Packet Rings (RPR) for metropolitan area networks. Its feature-rich design supports spatial reuse protocol (SRP) at speeds up to 10 Gbit/s. It incorporates packet support for both POS and native Ethernet with the flexibility to transport across SONET, DWDM or dark fiber. The Infineon Resilient Ring Processor is uniquely positioned to enable cost-effective resiliency and QoS for growing, high-speed IP networks.



Key Features

- High speed SRP MAC
- Up to OC-192 (10 Gbit/s) throughput
- Supports SRP, POS, Native Ethernet
- 1 MB low-priority transit buffer
- 32 KB high-priority transit buffer
- Giant, runt and short packet filters
- Supports IPS and topology discovery
- 899-pin Hyper BGA package

Specifications

Modes of Operation

- Dual ring mode
- Wrap mode
- Pass-through mode
- Transparent mode
- Passive and active sniffer modes

Operational Speeds

- OC-192
- OC-48

Packet Formats

- SRP
- Pseudo-SRP
- POS (in transparent mode)
- Native Ethernet

RX/TX Framer Host Interface

- 64-bits HSTL @200 MHz
- OIF SPI-4 Phase 1 compliant interface

- Giant, runt and short packet filtering with PM counters
- Data and control parity bit checking with PM counters
- Traffic flow monitoring
- Host-side leaky bucket rate limiters high/low priority
- Data parity fault insertion for system and software test
- Counters for high/low priority unicast/multicast packets and bytes

Lookup / Statistics **CAM Functions**

- 1024 Double (source, destination or both) address entries
- 1024 Double address counters
- CAM S/W features: read/write/ probe/reset individual entries
- 8 coarse multicast address filters
- for individual addresses

Transit Buffer

- Internal source and sink for usage packets
- Internal 1 MB low and 32 KB high priority buffers
- Counters for high/low priority
- unicast/multicast packets and bytes Counters for min, max and average
- delay in transit buffers

MATE Interface

- XGMII 10 gigabit interface
- 4, 8-bit channels at 312.5 MHz
- (10.0 Gbit/s total capacity) Automatic pass-through/wrap/ transparent mode communication
- Requires only 1 standard SERDES for inter-board communication
- Loss of sync detection with performance counters
- CRC detection

Microprocessor Interface

- 16-bit, asynchronous interface, up to 100 MHz
- Multiple interrupt reporting
- Send and receive buffers for IPS and topology packets

Electrical/Mechanical/Thermal

- 1.5/1.8/3.3 V power supplies
- 899-pin Hyper BGA Flip Chip package
- -40 °C to 85 °C operation
- ~5.18 W

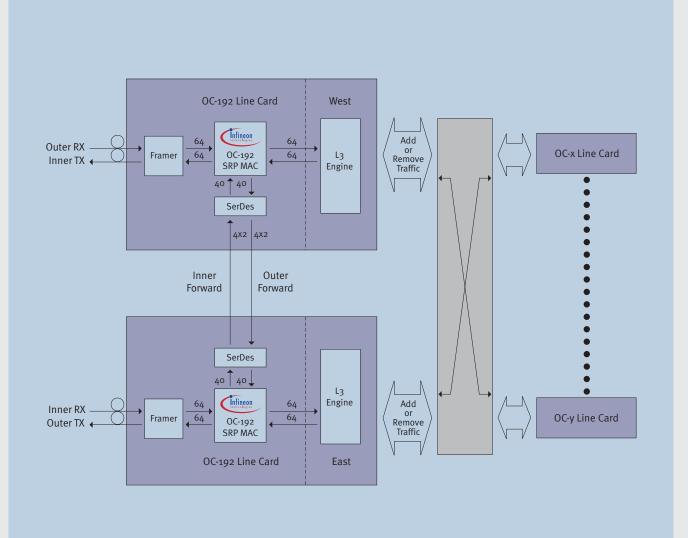
Other

- JTAG Compliant
- 100 MHz or 200 MHz reference clock
- Hard and soft reset
- CRC generation and checking
- Extensive loopback features for testing

Rhea Resilient Ring Processor OC-48 / OC-192 SRP MAC



- - accept or reject on match
 - Multicast accept/reject capability



Block Diagram

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